IN THE CLAIMS

Please amend the claims as follows:

Claims 1-13 (Canceled).

Claim 14 (New): A process for forming bumps on electrode pads, for a wiring board including a substrate and a plurality of electrode pads, the process comprising:

(a) forming a laminated two-layer film on the wiring board and forming a pattern of apertures at positions corresponding to the electrode pads, the laminated two-layer film including a lower layer comprising an alkali-soluble radiation-nonsensitive resin composition and an upper layer comprising a negative radiation-sensitive resin composition;

(b) filling a low-melting metal in the aperture pattern;

(c) reflowing the low-melting metal by pressing or heating to form bumps; and

(d) peeling and removing the laminated two-layer film from the wiring board.

Claim 15 (New): The process for forming bumps according to claim 14, wherein the radiation-nonsensitive resin composition contains a compound having a phenolic hydroxyl group.

Claim 16 (New): The process for forming bumps according to claim 14, wherein the negative radiation-sensitive resin composition contains an acrylic resin.

Claim 17 (New): The process for forming bumps according to claim 14, wherein the lower layer of the laminated two-layer film is formed from the radiation-nonsensitive resin composition that is in a form of liquid or dry film.

Claim 18 (New): The process for forming bumps according to claim 14, wherein the upper layer of the laminated two-layer film is formed from the negative radiation-sensitive resin composition that is in a form of liquid or dry film.

Claim 19 (New): The process for forming bumps according to claim 14, wherein the laminated two-layer film comprises a two-layer dry film including the lower and upper layers.

Claim 20 (New): The process for forming bumps according to claim 14, wherein the peeling and removing is performed with use of a peeling apparatus having multistage immersion baths and comprises peeling the laminated two-layer film in a first bath containing an organic solvent, followed by cycle filtration of peeled pieces, and peeling the residual laminated film in a second and later baths filled with a peeling solution containing an organic alkali component.

Claim 21 (New): The process for forming bumps according to claim 14, wherein the peeling and removing is performed with use of a peeling apparatus having multistage immersion baths and comprises peeling the laminated two-layer film in a first bath containing dimethyl sulfoxide, followed by cycle filtration of peeled pieces, and peeling the residual laminated film in a second and later baths filled with a peeling solution containing an organic alkali component and dimethyl sulfoxide.

Claim 22 (New): The process for forming bumps according to claim 14, wherein the wiring board comprises a substrate comprising silicon wafer, and a plurality of electrode pads provided on a surface of the substrate.

Claim 23 (New): The process for forming bumps according to claim 14, wherein the wiring board comprises a substrate comprising silicon wafer, a plurality of electrode pads provided on a surface of the substrate, and a passivation film formed so as to embed side surfaces and end surfaces of the electrode pads.

Claim 24 (New): The process for forming bumps according to claim 14, wherein the wiring board comprises a substrate comprising glass epoxy resin or bismaleimide-triadine resin, and a plurality of electrode pads.

Claim 25 (New): The process for forming bumps according to claim 14, wherein the wiring board comprises a substrate comprising glass epoxy resin or bismaleimide-triadine resin, an insulating resin interlayer and a conductive circuit formed on the substrate, and a plurality of electrode pads provided on the conductive circuit.

Claim 26 (New): The process for forming bumps according to claim 14, wherein the low-melting metal is solder.